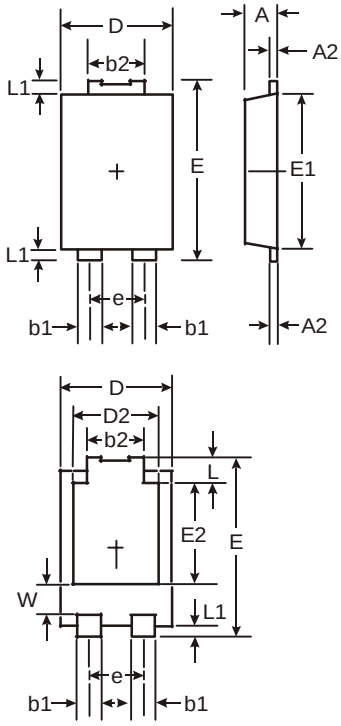
New Product Announcement
December 6, 2005

Announcing Expansions of Popular PowerDI™5 Product Line into Standard Recovery Rectifiers



Dim	Min	Max
A	1.05	1.15
A2	0.33	0.43
b1	0.80	0.99
b2	1.70	1.88
D	3.90	4.05
D2	3.05 NOM	
E	6.40	6.60
e	1.84 NOM	
E1	5.30	5.45
E2	3.55 NOM	
L	0.75	0.95
L1	0.50	0.65
W	1.20	1.50
All Dimensions in mm		

Diodes, Inc. patent-pending flat lead frame heat-sink solder pad results in higher power dissipation and surge capabilities in a compact low profile package

Product Highlights

- Small footprint, low profile package is ideal for space-constrained applications, such as portable electronics.
- Qualified to rigorous AEC-Q101 automotive standards to ensure high reliability.
- Excellent stability even under high ambient temperatures and reverse bias up to 400 Volts.
- RoHS Compliant: Lead free terminal plating and green molding compound assure compliance to the highest environmental standards.

Availability

- **Samples:** *Now* Available!
- **Production Quantity Lead Time:** 6 – 10 weeks
- **Data Sheets Available *NOW* at:** **www.diodes.com**

To download selected data sheet, enter p/n in our website Product Data Sheet search, or click**:**

PDR3G	3 Ampere / 400 Volts
PDR5G	5 Ampere / 400 Volts

PowerDI is a trademark of Diodes Incorporated.

Crosses to Other Manufacturers' Parts

Diodes' "New" PowerDI™5 products are thermally efficient replacements for the following devices:

Diodes, Inc.	Vishay-GS		Diodes, Inc.	
P/N	P/N	Package	P/N	Package
PDR3G	S3G	SMC	S3GB / S3G	SMB / SMC
PDR5G			S5GC	SMC

Dimensional Highlights

- Low profile: Only 1.1mm tall, ideal for height limited applications.
  Compare with 2.3mm for SMC and DPAK, and 4.4mm for D^2PAK.
- Small footprint: Occupies only 23.8mm^2 of PCB area, which can be compared with:
  - 47mm^2 for SMC (PowerDI™5 consumes 49% less area than SMC)
  - 61.5mm^2 for DPAK (PowerDI™5 consumes 55% less area than DPAK)

Thermal Performance Benefits

- **Twice the Power Density of Competitive Package Types** --
  Highest power density package: 55mW/mm^2, which can be compared with:
  - 25mW /mm^2 for SMC
  - 28 mW /mm^2 for DPAK
- **Up to 50% Lower Thermal Resistance than Competitive Package Types** --
  Thermally efficient package: $R_{\theta JS}$ = 1.5 - 6.0°C/W, which can be compared with:
  - 10 - 15°C/W for SMC
  - 2.4 - 6.0°C/W for DPAK

Solderability & Environmental Highlights

- RoHS Compliant
- "Green" (No Bromine, Antimony) Molding Compound
- Pb-Free, 100% Matte Tin Plating
- Withstands 260°C Solder Reflow
- Meets Moisture Sensitivity Level (MSL) 1

End Equipment Applications

- Automotive
- Disk drives
- Inverters
- Power management circuits
- Industrial controls
- Set top boxes
- Networking equipment, routers, hubs
- Computer peripherals; printers

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